TOSHIBA Intelligent Power Device Silicon Monolithic Power MOS Integrated Circuit

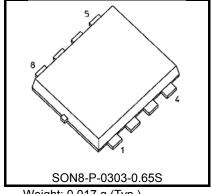
# TPD7104AF

#### 1 channel High-Side N channel Power MOSFET Gate Driver

TPD7104AF is a 1channel high-side N channel power MOSFET gate driver. This IC contains a charge pump circuit, allowing easy configuration of a high-side switch for large-current applications.

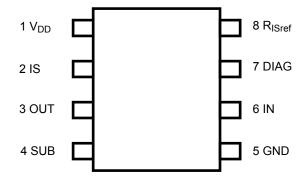
#### **Features**

- Charge pump circuit is built in
- Built-in short circuit and reverse battery protection
- Housed in the PS-8 package and supplied in embossed carrier tape

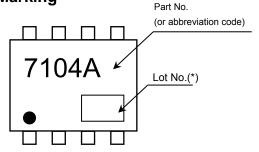


Weight: 0.017 g (Typ.)

#### Pin Assignment (top view)

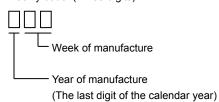


#### Marking



Note: • on the lower left of the marking indicates Pin 1

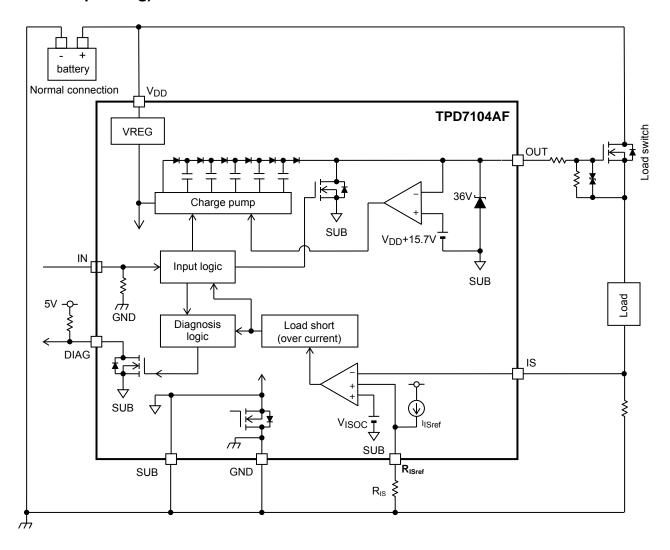
\*Weekly code: (Three digits)



Note: That because of its MOS structure, this product is sensitive to static electricity

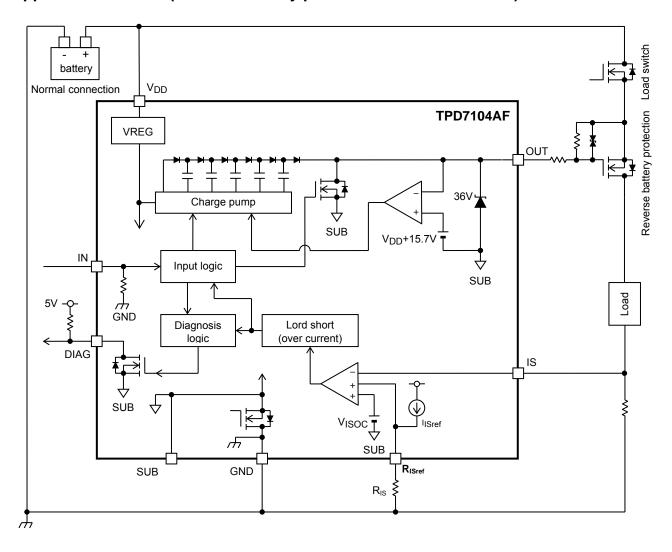
Start of commercial production 2015-08

# Block Diagram / Application circuit 1 (load switch circuit Reverse battery protection un-corresponding)



2 2016-05-19

# Application circuit 2 ( Reverse battery protection circuit " FET off")



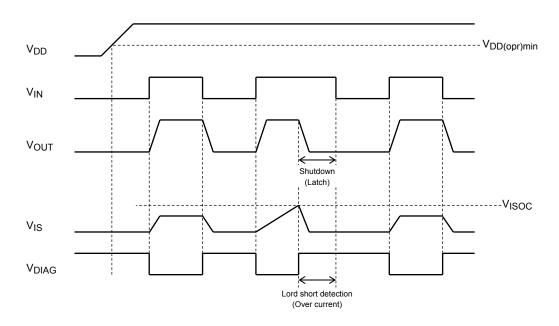
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## **Pin Description**

Pin No.	Symbol	Function				
1	$V_{DD}$	Power supply pin.				
2	IS	Detection pin for short circuit. If short circuit detection is not used, IS pin connect to GND.				
3	OUT	Output pin for an external MOSFET drive. State is off if detect short circuit.				
4	SUB	Please use open if use protection for reverse connection of power supply.  If protection for reverse connection of power supply is not used, SUB pin connect to GND.				
5	GND	Ground pin.				
6	IN	Input pin. IN has a pull-down resistor.				
7	DIAG	Diagnosis detection pin. It is open drain composition. Output is inverted if detect short circuit.				
8	R <sub>ISref</sub>	Adjust pin for sense level for short circuit detection. If R <sub>ISref</sub> is not used, R <sub>ISref</sub> pin is open.				

# **Timing Chart**



Note: Output shut down when it detects short circuit and becomes latch state and protects outside MOSFET. DIAG becomes H-state, and makes input L-state when reset the latch circuit.

#### **Truth Table**

V <sub>IN</sub>	V <sub>OUT</sub>	Charge pump	V <sub>IS</sub> (Note 1)	V <sub>DIAG</sub>	Mode
L	L	Charge pump stop (oscillation is stopped)	L	H (Note 2)	Normal
Н	Н	Charge pump operation.	L	L	
L	L	Charge pump stop (oscillation is stopped)	Н	H (Note 2)	l and about
Н	L	Charge pump stop (oscillation is stopped)	Н	H (Note 2)	Lord short
-	Hz (Note 3)	-	-	Hz (Note 3)	Reverse batttery (SUB pin open)

Note 1: V<sub>IS</sub>: Load short detection voltage.

Note 2: The Diag Output is a Nch open drain and it is OFF state at the time of  $V_{DIAG}$  = "H".

Note 3: Hz : High impedance.

#### Absolute Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rating	Unit	Remarks	
Dower cumply voltage	DC	$V_{DD(1)}$	-0.3 to 24	V	-	
Power supply voltage	Pulse	$V_{DD(2)}$	40	V	t=300ms single pulse	
Power supply reverse connection		-V <sub>DD(3)</sub>	18	V	SUB open	
Input voltage		V <sub>IN</sub>	-0.3 to 6	V	-	
Output source current		I <sub>OUT(-)</sub>	Internal capacity	mA	Source current	
Output sink current		I <sub>OUT(+)</sub>	5	mA	Sink current	
IS pin voltage		V <sub>IS</sub>	-0.3 to 6	V	-	
Diagnosis output voltage		$V_{DIAG}$	-0.3 to 6 V		-	
Diagnosis pin current		I <sub>DIAG</sub>	5	5 mA		
Power dissipation (Note1-a)		P <sub>D(1)</sub>	0.7	W	-	
Power dissipation (Note	e1-b)	P <sub>D(2)</sub>	0.35 W		-	
Operateing temperature		T <sub>opr</sub>	-40 to 125 °C		-	
Junction temperature		T <sub>j</sub>	150	150 °C		
Strage temerature		T <sub>stg</sub>	-55 to 150	-		

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings and the operating ranges.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

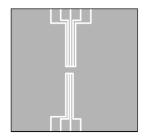
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#### **Thermal Resistance**

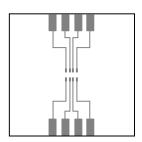
Characteristics	Symbol	Rating	unit	
Thermal registeres junction to embient	Б	178.6(Note 1-a)	°C / W	
Thermal resistance, junction to ambient	$R_{th (j-a)}$	357.2(Note 1-b)	C/W	

Note 1:

(Note 1-a) Glass epoxy board



Glass epoxy board Material: FR-4 25.4mm×25.4mm×0.8mm (Note 1-b) Glass epoxy board



Glass epoxy board Material: FR-4 25.4mm×25.4mm×0.8mm



## Electrical Characteristics (Unless otherwise specified, $T_j$ = -40 to 125°C, $V_{DD}$ = 5 to 18V)

Characteristics	Symbol	Pin	Test Condition	Min	Тур.	Max	Unit	
Operating supply voltage	$V_{\text{DD(opr)}}$	$V_{DD}$	-	5	12	18	V	
Cupply ourrent	I <sub>DD(off)</sub>	$V_{DD}$	$V_{DD} = 12V, V_{IN} = V_{IL}, T_j = 25^{\circ}C$	-	0.7	3	mA	
Supply current	I <sub>DD(on)</sub>	$V_{DD}$	V <sub>IN</sub> = V <sub>IH</sub> , output is open circuit	-	-	5	mA	
Innut valtage	V <sub>IH</sub>	IN	-	2.5	-	-	. V	
Input voltage	V <sub>IL</sub>	IIN	-	-	-	1.5	V	
Input ourrant	I <sub>IH</sub>	INI	V <sub>IN</sub> = 5V	-	19	50		
Input current	I <sub>IL</sub>	IN	V <sub>IN</sub> = 0V	-1	-	1	μΑ	
Output voltage	V <sub>OUTH1</sub>	OUT	$V_{DD} = 5V$ , $V_{IN} = V_{IH}$ , $I_{OUT} = -100\mu A$	V <sub>DD</sub> +8	V <sub>DD</sub> +13	V <sub>DD</sub> +18	V	
Output voltage	V <sub>OUTH2</sub>	OUT	$V_{DD} = 8 \text{ to } 18V, V_{IN} = V_{IH},$ $I_{OUT} = -100\mu\text{A}$	V <sub>DD</sub> +10	V <sub>DD</sub> +15.7	V <sub>DD</sub> +18	٧	
Output clamp voltage	Output clamp voltage $V_{clamp}$ OUT $V_{IN} = V_{IH}$		$V_{IN} = V_{IH}$	31	36	40	V	
Output resistance	R <sub>SINK</sub>	OUT	$V_{IN} = V_{IL}$ , $I_{OUT} = 1mA$	-	510	800	Ω	
Diagnosis output leakage current	I <sub>DIAGH</sub>	DIAG	$V_{IN} = V_{IL}, V_{DIAG} = 5V$	-	-	10	μΑ	
Diagnosis output voltage	$V_{DIAGL}$	DIAG	$V_{IN} = V_{IH}$ , $I_{DIAG} = 500 \mu A$	-	0.22	0.4	V	
Short circuit detection voltage	V <sub>ISOC</sub>	R <sub>ISref</sub>	V <sub>DD</sub> = 12V, R <sub>ISref</sub> pin is open circuit	0.8	1.02	1.2	V	
	I <sub>ISref(1)</sub>	R <sub>ISref</sub>	V <sub>RISref</sub> = 0.2V	-60	-38	-20	μA	
R <sub>ISref</sub> pin output current	I <sub>ISref(2)</sub>	R <sub>ISref</sub>	V <sub>RISref</sub> = 0.4V	-60	-38	-20	μA	
	I <sub>ISref(3)</sub>	R <sub>ISref</sub>	V <sub>RISref</sub> = 0.6V	-60	-38	-20	μA	
Cuitabina tima	t <sub>on</sub>	OUT	Refer to Test circuit 1 , T <sub>j</sub> = 25°C	-	450	800	μs	
Switching time	t <sub>off</sub>	OUT		-	480	800		
Output current for reverse	I <sub>REV(1)</sub>	OUT	Refer to Test circuit 2 V <sub>DD</sub> =-5 to -18V, T <sub>j</sub> = 25°C	-1	-	-	μΑ	
connection	I <sub>REV(2)</sub>	OUT	Refer to Test circuit 2 V <sub>DD</sub> =-5 to -18V, T <sub>j</sub> = -40 to 125°C	-10	-	-1	μΑ	

Note2 : Typical condition is  $V_{DD}$ =12V,  $T_i$ =25°C.

Note3: The current detection voltage is controllable, when connecting resistance to R<sub>ISref</sub> pin.

But, when  $V_{\text{RISref}}(R_{\text{IS}} \times I_{\text{ISref}})$  is over  $V_{\text{ISOC}}$ , the current detection voltage is  $V_{\text{ISOC}}$ .

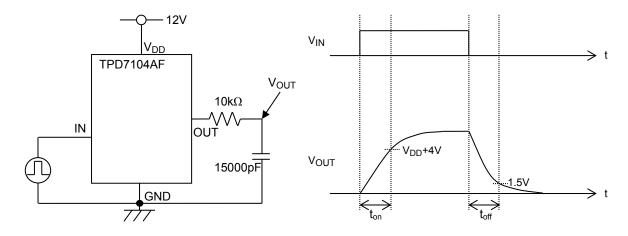
Note4: About the charge pump voltage

So as not to apply over-voltage to the gate-source voltage( $V_{GS}$ ) of external power MOSFET, and so as to become the best driving voltage, the clamping circuit is built into.

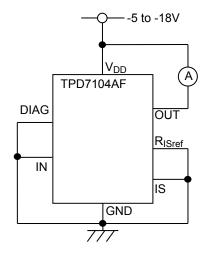
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And it doesn't output over 36V(Typ.), because of protection of itself.

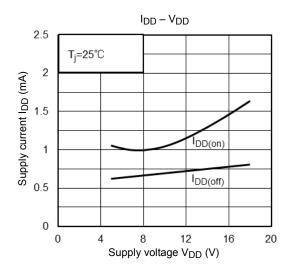
#### Test circuit 1 for switching time

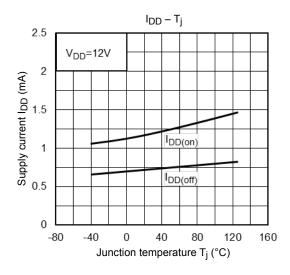


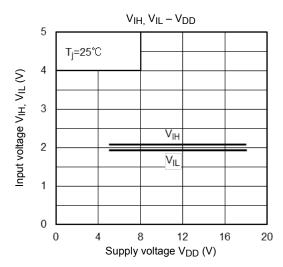
#### Test circuit 2 for Output current for reverse connection

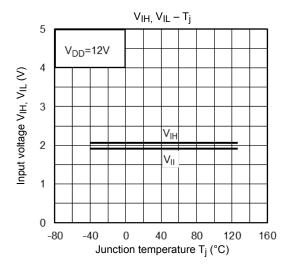


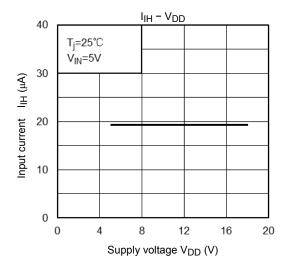
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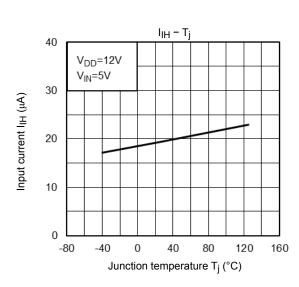


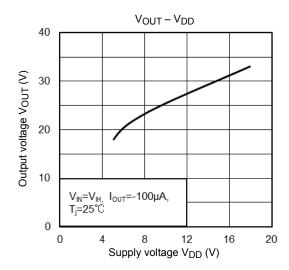


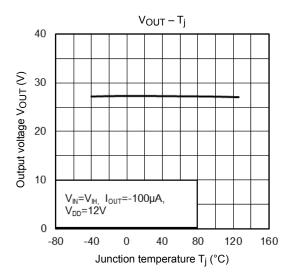


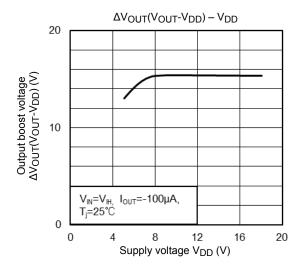


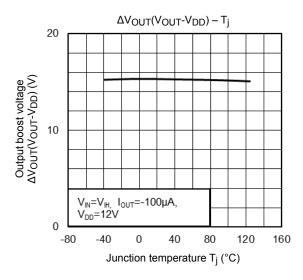


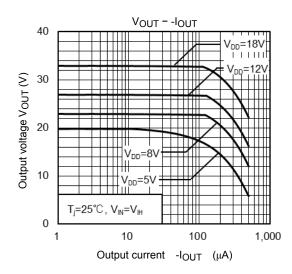


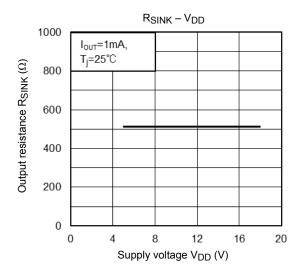


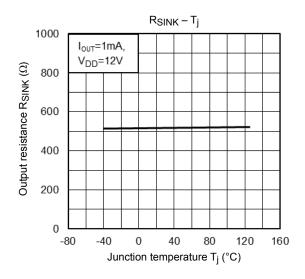


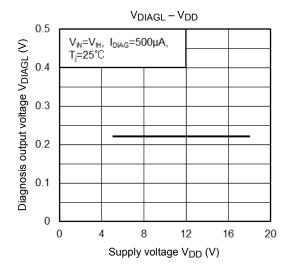


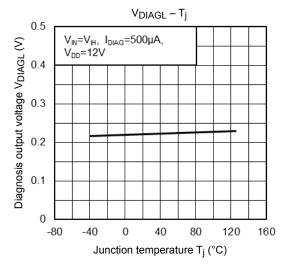


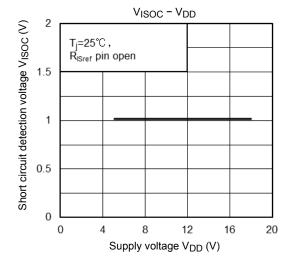


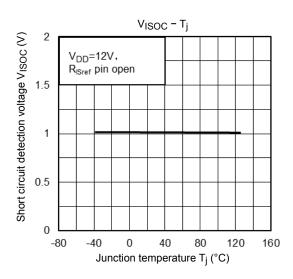




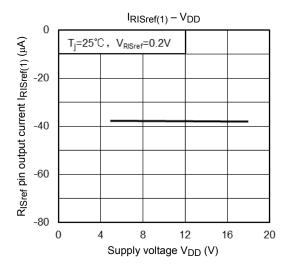


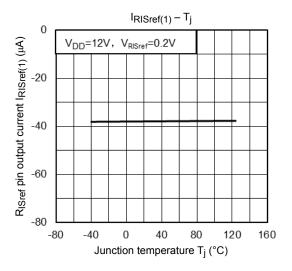


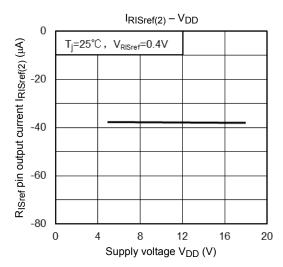


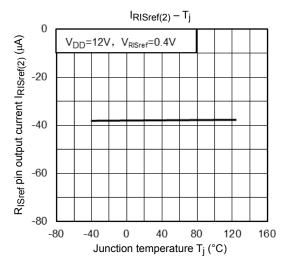


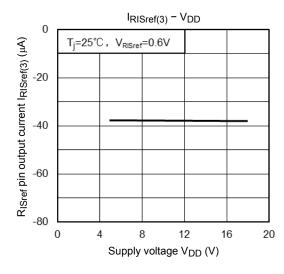
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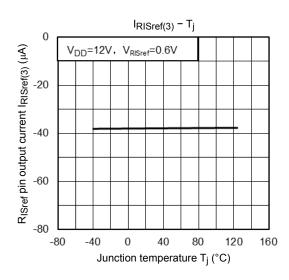


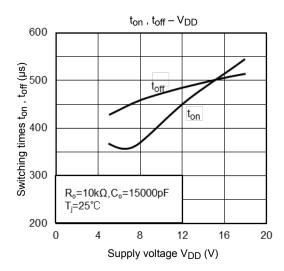


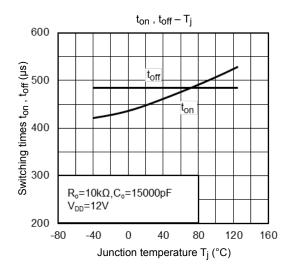


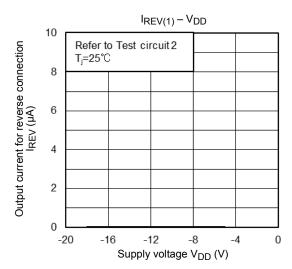


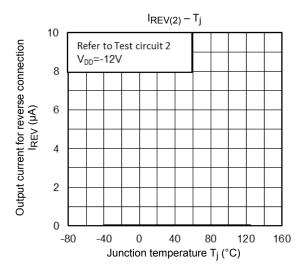


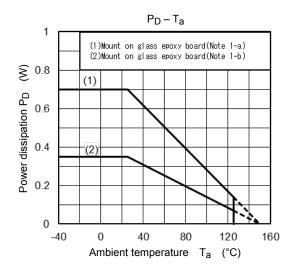










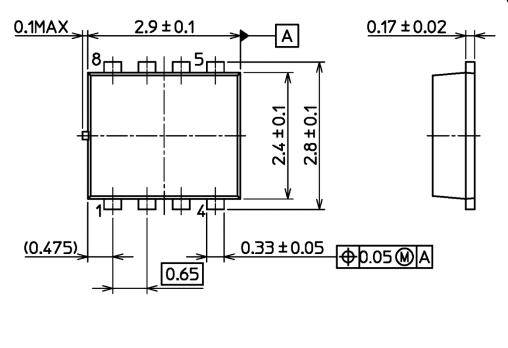


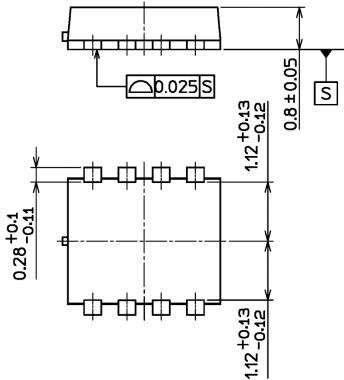


#### **Package Dimensions**

SON8-P-0303-0.65S

Unit: mm





Weight: 0.017g(typ.)

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